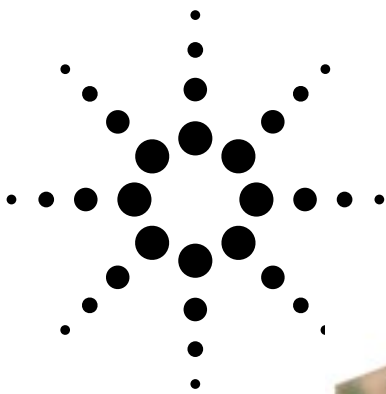


Agilent HSMF-C165, C166, C167 Miniature Bi-Color Surface Mount Chip LEDs Data Sheet



Description

The HSMF-C16x series of bicolor chip-type LEDs is designed in an ultra small package for miniaturization. It is the first of its kind to achieve such small packaging for 2 dies.

The small size, narrow footprint, and low profile make this series of LEDs excellent for backlighting, status indication, and front panel illumination applications.

Features

- Small 1.6 x 0.8 mm footprint
- Diffused optics
- Operating temperature range of -30°C to $+85^{\circ}\text{C}$
- Compatible with reflow soldering
- Three color combinations available: red/green, yellow/green, orange/green
- Available in 8 mm tape on 7" (178 mm) diameter reels

Applications

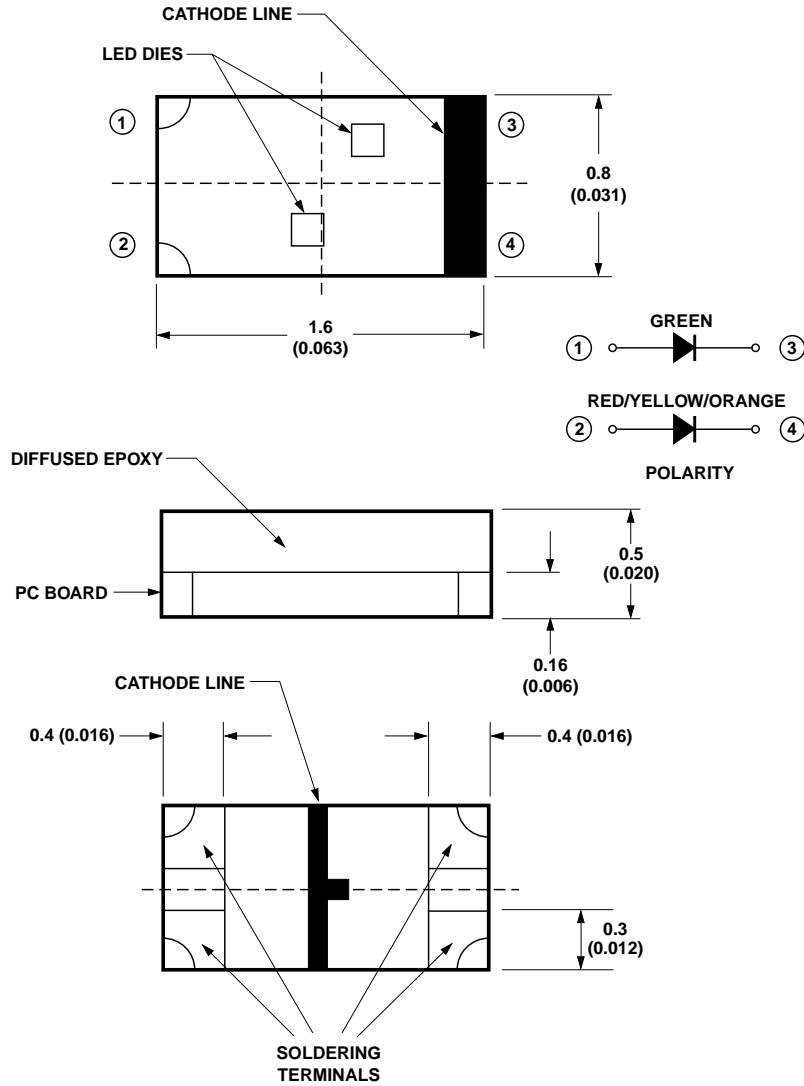
- Keypad backlighting
- Symbol backlighting
- LCD backlighting
- Status indication
- Front panel indicator

Device Selection Guide

| Part Number | Color | Parts per Reel |
|-------------|---------------------------|----------------|
| HSMF-C165 | High Efficiency Red/Green | 4000 |
| HSMF-C166 | Yellow/Green | 4000 |
| HSMF-C167 | Orange/Green | 4000 |



Package Dimensions



- NOTES:**
1. ALL DIMENSIONS IN MILLIMETERS (INCHES).
 2. TOLERANCE IS ± 0.1 mm (± 0.004 IN.) UNLESS OTHERWISE SPECIFIED.

Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

| Parameter | HSMF-C165/166/167 | Units |
|---|---|------------------|
| DC Forward Current [1] | 20 | mA |
| Peak Pulsing Current[2] | 100 | mA |
| Power Dissipation | 52 | mW |
| Reverse Voltage ($I_R = 100 \mu\text{A}$) | 5 | V |
| LED Junction Temperature | 95 | $^\circ\text{C}$ |
| Operating Temperature Range | -30 to +85 | $^\circ\text{C}$ |
| Storage Temperature Range | -40 to +85 | $^\circ\text{C}$ |
| Soldering Temperature | See reflow soldering profile (Figure 6) | |

Notes:

- Derate linearly as shown in Figure 4.
- Pulse condition of 1/10 duty and 0.1 ms width.

Electrical Characteristics at $T_A = 25^\circ\text{C}$

| Color | Forward Voltage V_F (Volts) @ $I_F = 20 \text{ mA}$ | | Reverse Breakdown V_R (Volts) @ $I_R = 100 \mu\text{A}$ | Capacitance C (pF), @ $V_F = 0$, $f = 1 \text{ MHz}$ | Thermal Resistance $R_{\theta_{J-PIN}}$ ($^\circ\text{C/W}$) |
|--------|---|------|---|---|--|
| | Typ. | Max. | Min. | Typ. | Typ. |
| HER | 2.1 | 2.6 | 5 | 5 | 325 |
| Orange | 2.2 | 2.6 | 5 | 7 | 325 |
| Yellow | 2.1 | 2.6 | 5 | 6 | 325 |
| Green | 2.2 | 2.6 | 5 | 9 | 325 |

Optical Characteristics at $T_A = 25^\circ\text{C}$

| Color | Luminous Intensity I_V (mcd) @ 20 mA[1] | | Peak Wavelength λ_{peak} (nm) | Color, Dominant Wavelength λ_d [2] (nm) | Viewing Angle $2 \theta_{1/2}$ Degrees[3] |
|--------|---|------|--|--|---|
| | Min. | Typ. | Typ. | Typ. | Typ. |
| HER | 2.5 | 10.0 | 630 | 626 | 120 |
| Orange | 2.5 | 8.0 | 605 | 604 | 120 |
| Yellow | 2.5 | 8.0 | 589 | 586 | 120 |
| Green | 4.0 | 15.0 | 570 | 572 | 120 |

Notes:

- The luminous intensity, I_V , is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the lamp package.
- The dominant wavelength, λ_d , is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.
- $\theta_{1/2}$ is the off-axis angle where the luminous intensity is 1/2 the peak intensity.

Color Bin Limits

Green Color Bins^[1]

| Bin ID | Dom. Wavelength (nm) | |
|--------|----------------------|------|
| | Min. | Max. |
| A | 561 | 565 |
| B | 564 | 568 |
| C | 567 | 571 |
| D | 570 | 574 |
| E | 573 | 577 |

Orange Color Bins^[1]

| Bin ID | Dom. Wavelength (nm) | |
|--------|----------------------|-------|
| | Min. | Max. |
| A | 596.0 | 601.0 |
| B | 599.0 | 604.0 |
| C | 602.0 | 607.0 |
| D | 605.0 | 610.0 |
| E | 608.0 | 613.0 |
| F | 611.0 | 616.0 |

Yellow/Amber Color Bins^[1]

| Bin ID | Dom. Wavelength (nm) | |
|--------|----------------------|-------|
| | Min. | Max. |
| A | 581.5 | 585.0 |
| B | 584.0 | 587.5 |
| C | 586.5 | 590.0 |
| D | 589.5 | 592.5 |
| E | 591.5 | 595.0 |
| F | 594.0 | 597.5 |

Light Intensity (Iv) Bin Limits^[1]

| Bin ID | Intensity (mcd) | | Bin ID | Intensity (mcd) | |
|--------|-----------------|------|--------|-----------------|--------|
| | Min. | Max. | | Min. | Max. |
| A | 0.10 | 0.20 | K | 6.30 | 12.50 |
| B | 0.16 | 0.32 | L | 10.00 | 20.00 |
| C | 0.25 | 0.50 | M | 16.00 | 32.00 |
| D | 0.40 | 0.80 | N | 25.00 | 50.00 |
| E | 0.63 | 1.25 | P | 40.00 | 80.00 |
| F | 1.00 | 2.00 | Q | 63.00 | 125.00 |
| G | 1.60 | 3.20 | R | 100.00 | 200.00 |
| H | 2.50 | 5.00 | S | 160.00 | 320.00 |
| J | 4.00 | 8.00 | T | 250.00 | 500.00 |

Note:

1. Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Agilent representative for information on currently available bins.

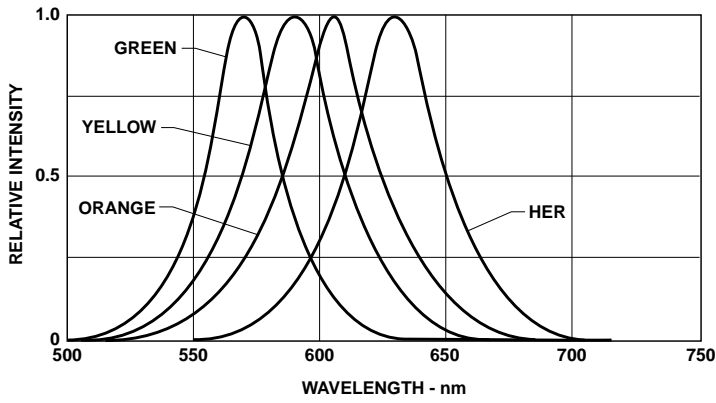


Figure 1. Relative intensity vs. wavelength.

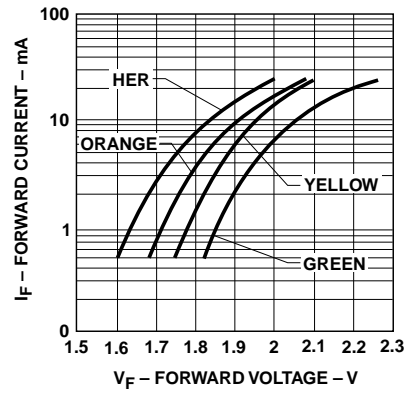


Figure 2. Forward current vs. forward voltage.

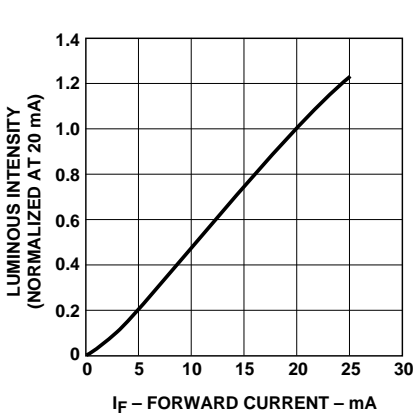


Figure 3. Luminous intensity vs. forward current.

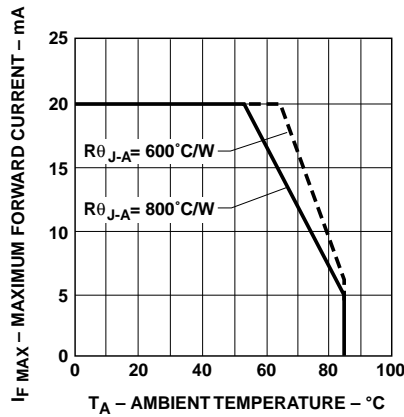


Figure 4. Maximum forward current vs. ambient temperature.

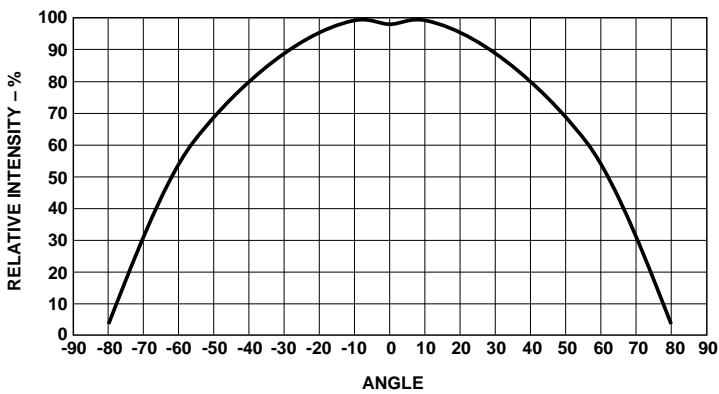


Figure 5. Relative intensity vs. angle.

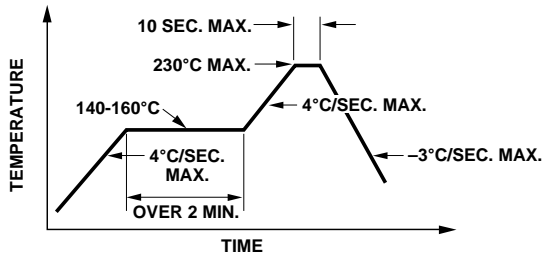


Figure 6. Recommended reflow soldering profile.

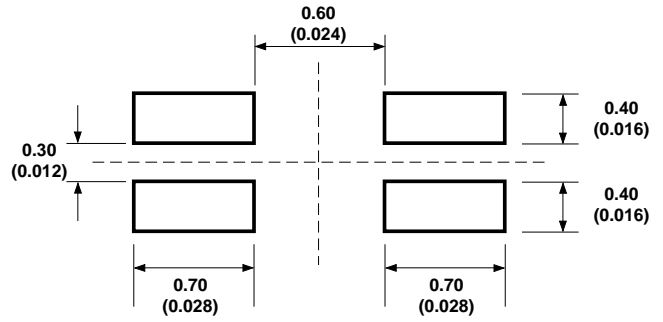


Figure 7. Recommended soldering pad pattern.

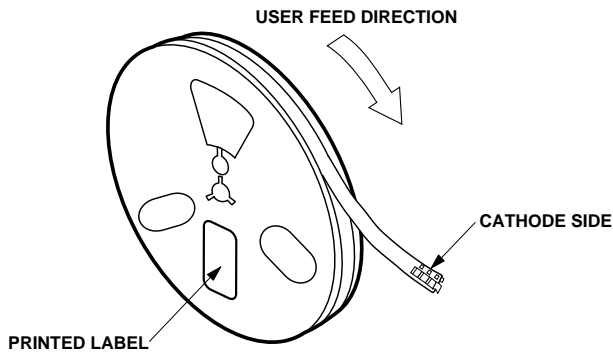


Figure 8. Reeling orientation.

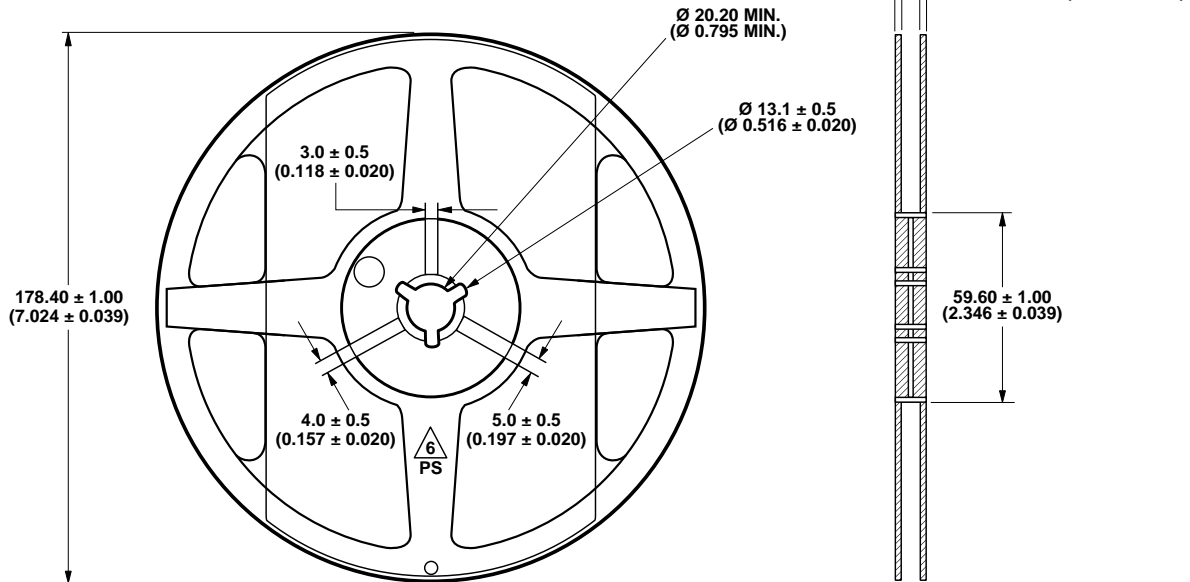


Figure 9. Reel dimensions.

NOTE:
1. ALL DIMENSIONS IN MILLIMETERS (INCHES).

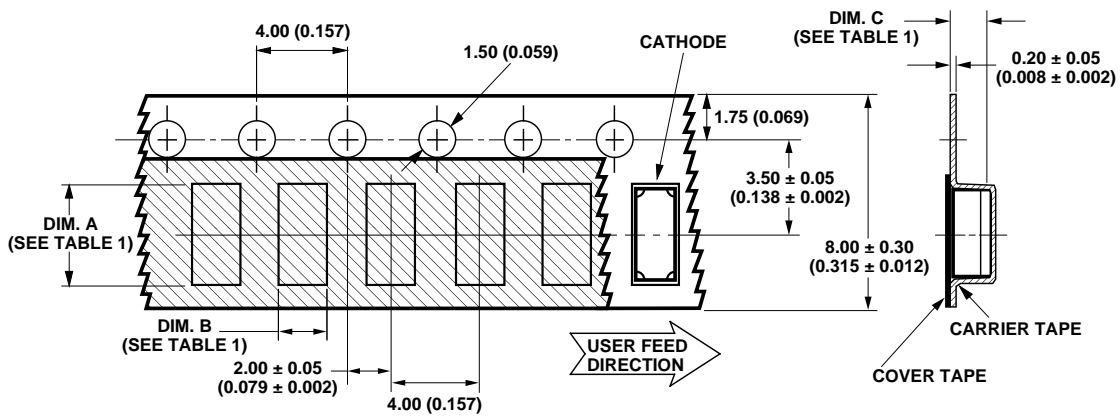


TABLE 1
DIMENSIONS IN MILLIMETERS (INCHES)

| PART NUMBER | DIM. A ± 0.10 (± 0.004) | DIM. B ± 0.10 (± 0.004) | DIM. C ± 0.10 (± 0.004) |
|------------------|----------------------------|----------------------------|----------------------------|
| HSMF-C16x SERIES | 1.80 (0.071) | 0.95 (0.037) | 0.60 (0.024) |

Figure 10. Tape dimensions.

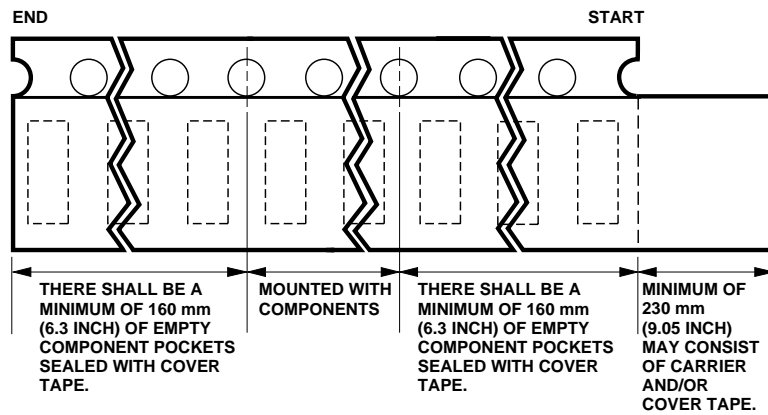


Figure 11. Tape leader and trailer dimensions.

- NOTES:
1. ALL DIMENSIONS IN MILLIMETERS (INCHES).
 2. TOLERANCE IS ± 0.1 mm (± 0.004 IN.) UNLESS OTHERWISE SPECIFIED.

Reflow Soldering

For more information on reflow soldering, refer to Application Note 1060, *Surface Mounting SMT LED Indicator Components*.

Storage Condition:

5 to 30°C @ 60% RH max.

Baking is required under the condition:

- a) the blue silica gel indicator becoming white/transparent color
- b) the pack has been open for more than 1 week

Baking recommended condition:
60 ± 5°C for 20 hours.

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